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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/693,460	10/27/2003	Hideaki Niimi	M1071.1873	2937
7590	09/08/2004		EXAMINER	
Edward A. Meilman DICKSTEIN SHAPIRO MORIN & OSHINSKY LLP 1177 Avenue of the Americas 41st floor New York, NY 10036-2714			MAYES, MELVIN C	
		ART UNIT	PAPER NUMBER	1734
DATE MAILED: 09/08/2004				

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary	Application No.	Applicant(s)
	10/693,460	NIIMI, HIDEAKI
	Examiner	Art Unit
	Melvin Curtis Mayes	1734

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address--

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) Responsive to communication(s) filed on 24 August 2004.
- 2a) This action is **FINAL**. 2b) This action is non-final.
- 3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) Claim(s) 5-9,11-15,17-20 and 22-24 is/are pending in the application.
- 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
- 5) Claim(s) _____ is/are allowed.
- 6) Claim(s) 5-7,20 and 22-24 is/are rejected.
- 7) Claim(s) 8,9,11-15 and 17-19 is/are objected to.
- 8) Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) The specification is objected to by the Examiner.
- 10) The drawing(s) filed on _____ is/are: a) accepted or b) objected to by the Examiner.
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
 - a) All b) Some * c) None of:
 1. Certified copies of the priority documents have been received.
 2. Certified copies of the priority documents have been received in Application No. _____.
 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).
- * See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- | | |
|--|---|
| 1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892) | 4) <input type="checkbox"/> Interview Summary (PTO-413) |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948) | Paper No(s)/Mail Date. _____ . |
| 3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)
Paper No(s)/Mail Date _____ . | 5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152) |
| | 6) <input type="checkbox"/> Other: _____ . |

DETAILED ACTION

Claim Rejections - 35 USC § 103

(1)

The text of those sections of Title 35, U.S. Code not included in this action can be found in a prior Office action.

(2)

Claims 5, 20, 23, 24 are rejected under 35 U.S.C. 103(a) as being unpatentable over JP 6-151103 in view of Dirstine 4,386,985.

JP 6-151103 discloses a method of making a laminated semiconductor constituent having positive resistance temperature comprising: forming a mixture including BaCO₃ (barium compound) and TiO₂ (titanium compound); baking (calcining) to form a semiconductive barium titanate powder (calcined product); forming semiconductor ceramic layers (ceramic green sheet) from slurry containing the powder; applying nickel-Pd paste on the ceramic layers to form internal electrodes; laminating the ceramic layers; baking in a reducing atmosphere; re-oxidizing; and forming external electrodes on the sintered body (computer translation). JP 6-151103 does not disclose providing a nickel compound in the mixture to be baked (calcined) to form the semiconductive barium titanate powder.

Dirstine teach that in manufacturing a ceramic capacitor from a barium titanate composition and nickel electrodes, the addition of nickel oxide in amounts of about 1 to 2 mol% to the composition optimizes the dielectric properties, in particular the room temperature dielectric constant, and maintains the integrity of the nickel electrodes co-fired with the green ceramic by preventing dissolution and degradation of the nickel

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electrodes. The nickel oxide (NiO) is added to the composition by mixing with the BaCO₃ and TiO₂ and calcining (col. 3, lines 29-40, col. 8, line 26 – col. 9, line 22).

It would have been obvious to one of ordinary skill in the art to have modified the method of JP '103 for making a laminated barium titanate semiconductor constituent having nickel internal electrodes by also providing nickel oxide (nickel compound) in the mixture with the barium compound and titanium compound to be calcined to form the powder, as taught by Dirstine, to optimize the dielectric properties, in particular the room temperature dielectric constant, and to maintain the integrity of the nickel electrodes co-fired with the green ceramic by preventing dissolution and degradation of the nickel electrodes.

(3)

Claims 6, 7 and 22 are rejected under 35 U.S.C. 103(a) as being unpatentable over the references as applied to claim 5 above, and further in view of JP 11-12033.

JP 11-12033 teaches that boron oxide is added to barium titanate semiconductor composition to lower the sintering temperature of the composition and to provide particle growth of uniform particle size by liquid phase sintering. Boron oxide is added to the BaCO₃ and TiO₂ before calcining so that the calcined composition contains 0.3-20 mol% boron oxide. The addition is boron oxide allows sintering of the composition at 1100-1200°C in 1 hour (computer translation).

It would have been obvious to one of ordinary skill in the art to have modified the method of the references as combined by also providing boron oxide (boron compound) in the mixture with the barium compound, titanium compound and nickel compound to be calcined, as taught by JP '033, to lower the sintering temperature of barium titanate

semiconductor composition and to provide particle growth of uniform particle size by liquid phase sintering. Providing the boron oxide in an amount in the range of 0.2 - 20 mol%, as claimed in Claim 7, would have been obvious to one of ordinary skill in the art, as JP '033 teaches to provide boron oxide so that the calcined composition contains 0.3-20 mol% boron oxide.

Performing the baking at a temperature in the range of 900-1300°C in the range of 0.5-5 hours, as claimed in Claim 22, would have been obvious to one of ordinary skill in the art, as JP '033 teaches that by providing boron oxide, the semiconductor composition can be sintered at 1100-1200°C in 1 hour.

(4)

Claims 5, 20, 23 and 24 are rejected under 35 U.S.C. 103(a) as being unpatentable over JP 6-151103 in view of either JP 63-312616 Abstract or JP 62-229602 Abstract.

JP 6-151103 discloses a method of making a laminated semiconductor constituent having positive resistance temperature comprising: forming a mixture including BaCO₃ (barium compound) and TiO₂ (titanium compound); baking to form a semiconductive barium titanate powder; forming semiconductor ceramic layers from slurry containing the powder; applying nickel-Pd paste on the ceramic layers to form internal electrodes; laminating the ceramic layers; baking in a reducing atmosphere; re-oxidizing; and forming external electrodes on the sintered body (computer translation). JP 6-151103 does not disclose providing a nickel compound in the mixture to be baked (calcined) to form the semiconductive barium titanate powder.

JP 63-312616 Abstract teaches that a barium titanate semiconductor composition which exhibits excellent nonlinearity and positive temperature coefficient contains as a

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third ingredient 0.005 – 1.5 mol% of at least one of ZnO, MnO, CoO, NiO, SnO₂ or Cr₂O₃.

JP 62-229602 Abstract teaches that a barium titanate composition for a reduction-oxidation type semiconductor capacitor of large capacity, high reliability and good temperature characteristics comprises 0.1-0.7 wt% Ni as NiO.

It would have been obvious to one of ordinary skill in the art to have modified the method of JP '103 for making a laminated barium titanate semiconductor constituent by also providing nickel oxide (nickel compound) in the mixture with the barium compound and titanium compound to be calcined to form the powder, as taught by either JP '616 or JP '602, as an ingredient that can also be provided in barium titanate semiconductor composition which exhibits excellent nonlinearity and positive temperature coefficient or which results in a reduction-oxidation type semiconductor capacitor of large capacity, high reliability and good temperature characteristics. Providing nickel oxide in a barium titanate semiconductor composition would have been obvious to one of ordinary skill in the art, as taught by either JP '616 or JP '602.

(5)

Claims 6 7, and 22 are rejected under 35 U.S.C. 103(a) as being unpatentable over JP 6-151103 in view of either JP 63-312616 Abstract or JP 62-229602 Abstract as applied to claim 5 above, and further in view of JP 11-12033.

JP 11-12033 teaches that boron oxide is added to barium titanate semiconductor composition to lower the sintering temperature of the composition and to provide particle growth of uniform particle size by liquid phase sintering. Boron oxide is added to the BaCO₃ and TiO₂ before calcining so that the calcined composition contains 0.3-20 mol%

boron oxide. The addition is boron oxide allows sintering of the composition at 1100-1200°C in 1 hour (computer translation).

It would have been obvious to one of ordinary skill in the art to have modified the method of the references as combined by also providing boron oxide (boron compound) in the mixture with the barium compound, titanium compound and nickel compound to be calcined, as taught by JP '033, to lower the sintering temperature of barium titanate semiconductor composition and to provide particle growth of uniform particle size by liquid phase sintering. Providing the boron oxide in an amount in the range of 0.2 - 20 mol%, as claimed in Claim 7, would have been obvious to one of ordinary skill in the art, as JP '033 teaches to provide boron oxide so that the calcined composition contains 0.3-20 mol% boron oxide.

Performing the baking at a temperature in the range of 900-1300°C in the range of 0.5-5 hours, as claimed in Claim 22, would have been obvious to one of ordinary skill in the art, as JP '033 teaches that by providing boron oxide, the semiconductor composition can be sintered at 1100-1200°C in 1 hour.

(6)

Claims 5, 20 and 22-24 are rejected under 35 U.S.C. 103(a) as being unpatentable over Ueno et al. 5,166,759 in view of Dirstine 4,386,985.

Ueno et al. 5,166,759 disclose a method of making a semiconductor-type laminated capacitor comprising: forming a mixture including BaO or BaCO₃ (barium compound) and TiO₂ (titanium compound); calcining the mixture to make a semiconductive powder; forming a raw sheet from the powder; printing inner electrode such as of nickel on the raw sheet; laminating raw sheets; sintering in a reducing

atmosphere at 1200-1350°C; re-oxidizing in air; and providing outer electrodes connected to the inner electrodes (col. 6, lines 6-66, col. 23, lines 5-54). Ueno et al. do not disclose providing a nickel compound in the mixture to be calcined to form the semiconductive powder.

Dirstine teach that in manufacturing a ceramic capacitor from a barium titanate composition and nickel electrodes, the addition of nickel oxide to the composition optimizes the dielectric properties, in particular the room temperature dielectric constant, and maintains the integrity of the nickel electrodes co-fired with the green ceramic by preventing dissolution and degradation of the nickel electrodes. The nickel oxide (NiO) is added to the composition by mixing with the BaCO₃ and TiO₂ and calcining (col. 3, lines 29-40, col. 8, line 26 – col. 9, line 22).

It would have been obvious to one of ordinary skill in the art to have modified the method of Ueno et al. for making a laminated barium titanate semiconductor capacitor having nickel internal electrodes by also providing nickel oxide (nickel compound) in the mixture with the barium compound and titanium compound to be calcined to form the powder, as taught by Dirstine, to optimize the dielectric properties, in particular the room temperature dielectric constant, and to maintain the integrity of the nickel electrodes co-fired with the green ceramic by preventing dissolution and degradation of the nickel electrodes.

Allowable Subject Matter

(7)

Claims 8, 9, 11-15 and 17-19 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

Response to Arguments

(8)

Applicant's arguments filed July 28, 2004 with respect to Claims 8 and 14 have been fully considered and are persuasive. The rejection of Claims 8 and 14 has been withdrawn.

Applicant's arguments filed July 28, 2004 with respect to Claim 5 have been fully considered but they are not persuasive.

Applicant argues that Dirstine discloses adding nickel oxide to optimize dielectric properties while the present invention is designed to provide a PCT semiconductive composition. Applicant argues that adding the nickel (nickel oxide) would clearly counteract the semiconductive properties which the present invention seeks to achieve.

(9)

The Examiner is not convinced that the addition of nickel oxide would counteract the semiconductive properties of the barium titanate composition. According to Dirstine, the addition of nickel oxide optimizes the dielectric properties, in particular the room temperature dielectric constant. It is not counteractive to provide a semiconductor composition with certain dielectric constant properties. This is evidenced by references

cited of interest, KR 9206732 Abstract, JP 59217322 Abstract and JP 55050615 which each teach of barium titanate semiconductor composition with high dielectric constant. Further, irregardless of Dirstine, Applicant has not provided any argument concerning the JP 63-312616 Abstract and JP 62-229602 Abstract references cited in paragraph (4) which each teach providing NiO in a barium titanate semiconductor composition.

Further, certain dielectric constant properties are not counteractive to the PTC properties of a semiconductive composition, as evidenced by the reference cited of interest DE 1646724 Abstract which teaches of PTC material with high dielectric constant. In fact PTC is related to dielectric constant in that PTC refers to "positive temperature coefficient of dielectric constant."

Conclusion

(10)

The prior art made of record and not relied upon is considered pertinent to applicant's disclosure.

The references disclose semiconductive or PTC compositions having certain dielectric constant properties.

(11)

THIS ACTION IS MADE FINAL. Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not

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mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

(12)

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Melvin Curtis Mayes whose telephone number is 571-272-1234. The examiner can normally be reached on Mon-Fri 7:30 AM - 4:00 PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Chris Fiorilla can be reached on 571-272-1187. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).



Melvin Curtis Mayes
Primary Examiner
Art Unit 1734

MCM
September 2, 2004